

规格书编号：

SPEC NO：

产品规格书

SPECIFICATION

CUSTOMER 客户： _____
PRODUCT 产品： _____ SAW FILTER _____
MODEL NO 型号： _____ HDBF07016A24 SMD-24 _____
PREPARED 编制： _____ 俞虹 _____ CHECKED 审核： _____ 邓攀 _____
APPROVED 批准： _____ 倪山林 _____ DATE 日期： _____ 2010-12-30 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07016A24 used for the page system.

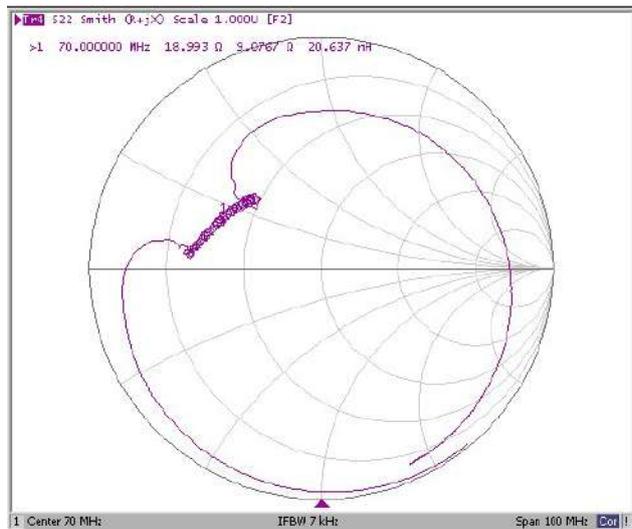
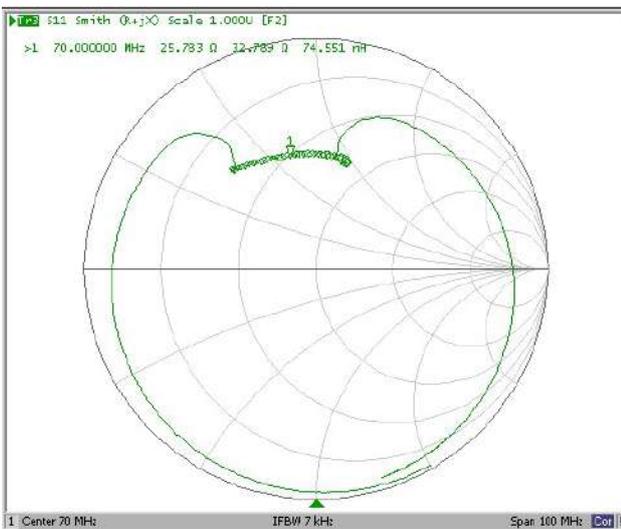
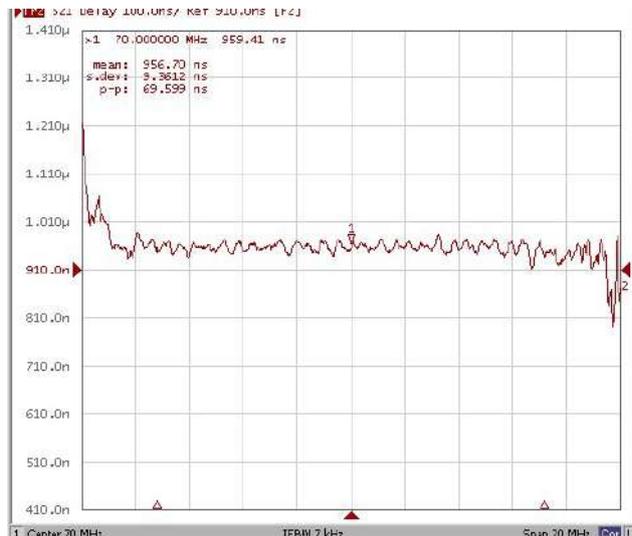
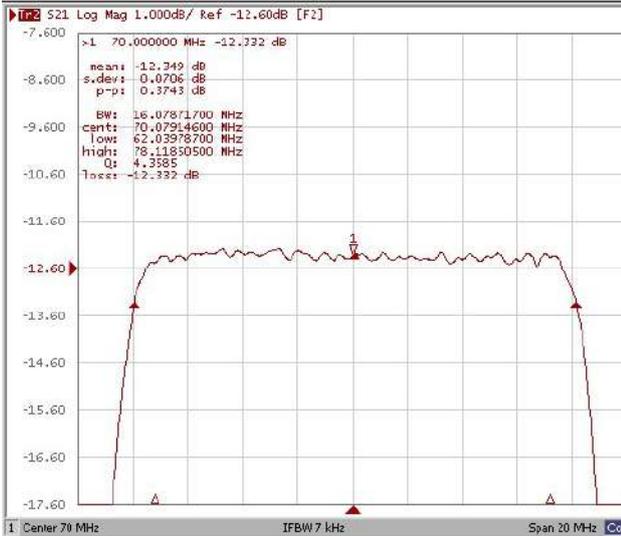
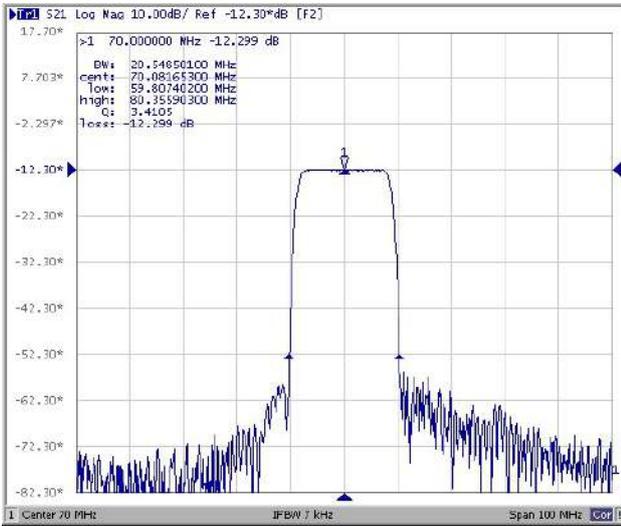
2. ELECTRICAL SPECIFICATION

Maximum incident power in passband	+10dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40°C to +85°C
Operation temperature range	-40°C to +85°C

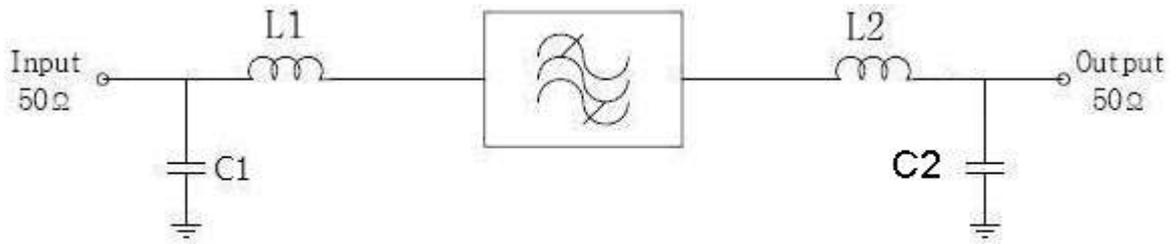
Electronic Characteristics

Parameter	Min.	Typical.	Max.	Unit
Center Frequency	69.8	70	70.2	MHz
Insertion loss		12.5	13.5	dB
-1 dB Bandwidth	15.5	16	-	MHz
-3 dB Bandwidth	16	16.9		MHz
-40 dB Bandwidth		21.2	22	MHz
Passband Variation		0.4	1.0	dB
Absolute Delay		0.96		us
Group delay Variation (F0 +/- 12MHz)		70	100	ns
Phase Linearity (F0 +/- 12MHz)		2.5	11.5	deg
Ultimate Rejection (Over F0 +/- 20MHz)	40	44		dB
Temperature Coefficient		-86		ppm/°C
Package Size	SMD 13.3mm*6.5mm			

Typical frequency response



3. TEST CIRCUIT

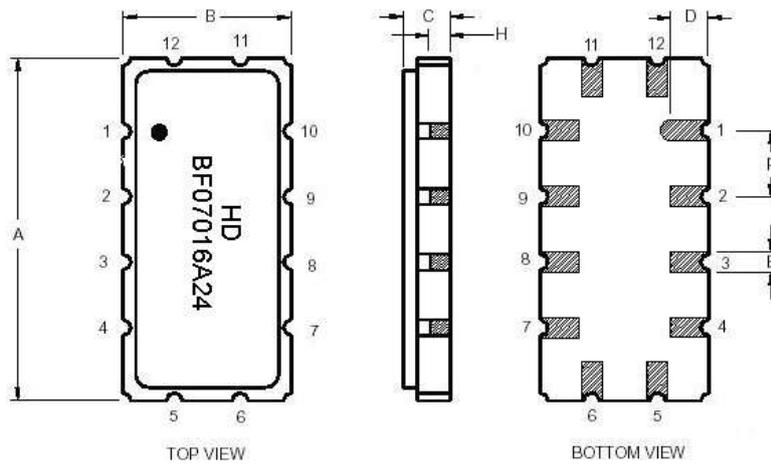


$$L1 = L2 = 150 \text{ nH}$$

$$C1 = C2 = 30 \text{ pF}$$

* Component values may change depending on board layout.

4. DIMENSION



Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
11	Input
5	Output
Other	Ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

5-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.